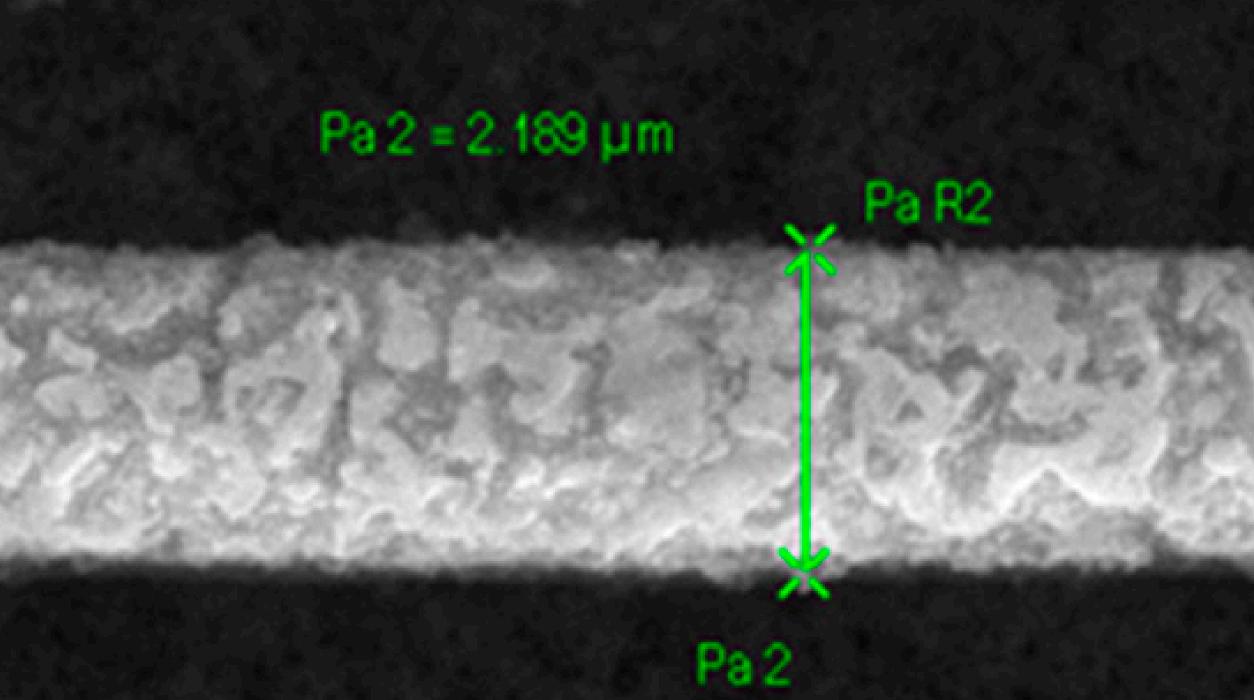
EXPT NovaBond® EX-S2

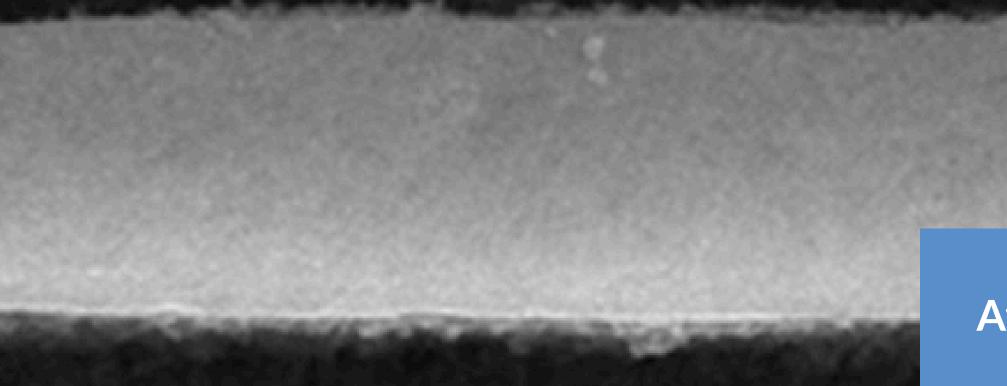


Atotech

ULTRA low roughness

bonding enhancement for IC substrates

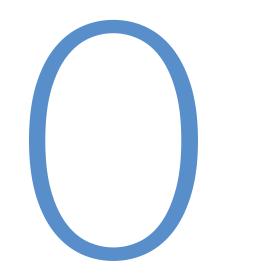




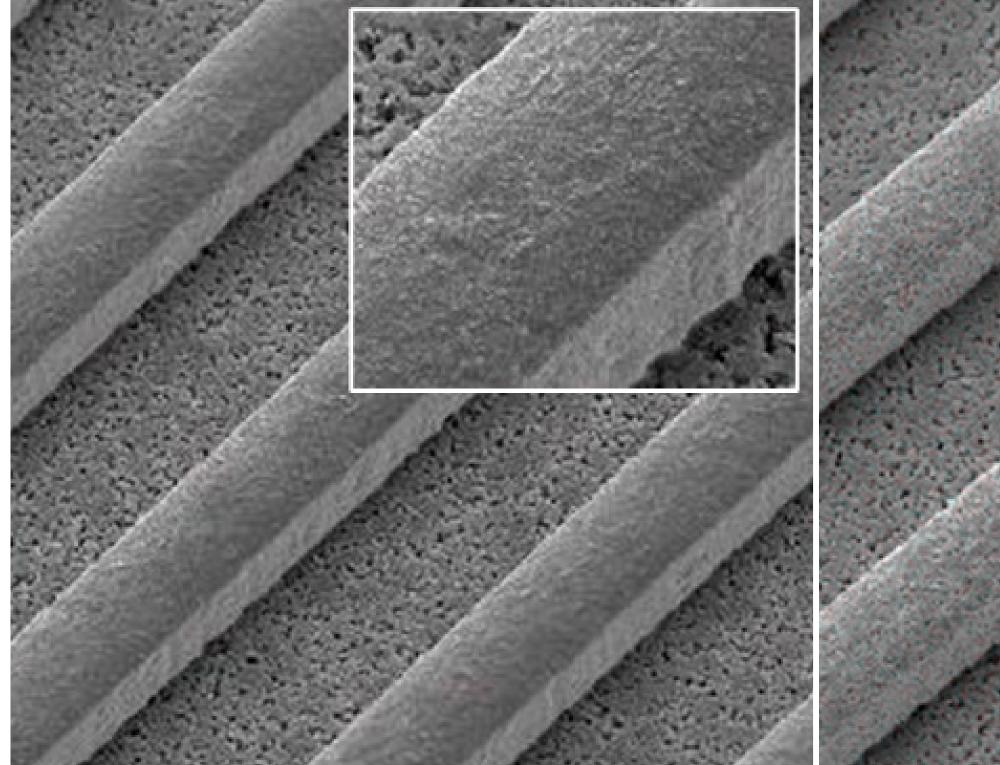
Pa₂

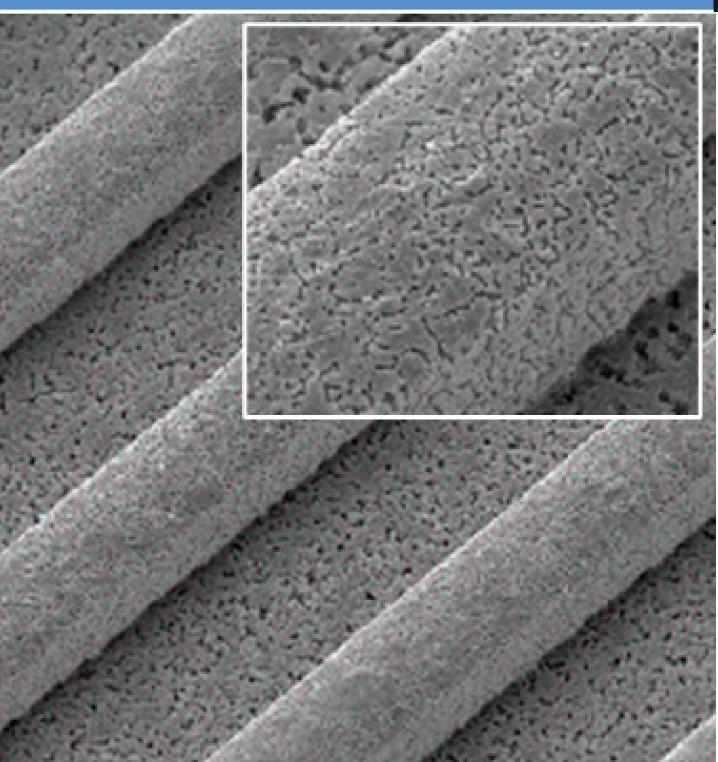
After cleaning / before etching

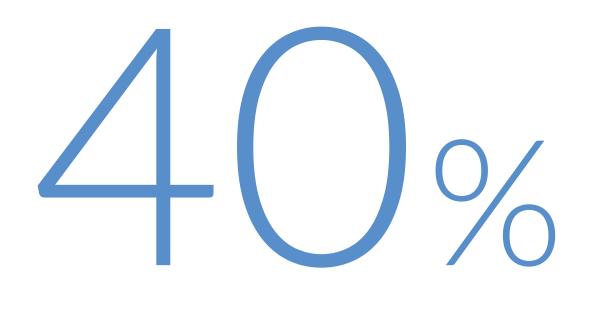
After 50-150 nm etching



line width reduction/ line height reduction







lower total costs of ownership

The most innovative IC substrate bonding enhancement

NovaBond[®] EX-S2 is our high-tech solution for IC substrate inner layer bonding. It combines the advantages of competing processes by applying a brand-new innovative technology that ensures high SI performance, thermal reliability and bond strength. This is achieved by creating a nano-roughness in symbiosis with a special patented silane, while not affecting the shape of the traces.

Features and benefits

- Uniform and constant nano-roughening regardless of copper surface type
- High compatibility to various high speed substrate materials
- Preserving conductor shape and size
- Very suitable for ultra fine line applications with L/S < 5/5 μm
- Signal integrity similar to non-treated; 2% better than low rougness oxide replacement
- Great peel strength